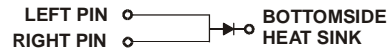
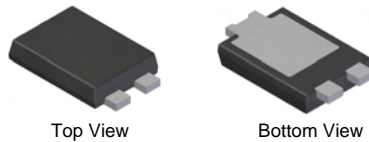


Features

- Designed as Bypass Diodes for Solar Panels
- Selectively Rated for 200°C Maximum Junction Temperature for High Thermal Reliability
- Patented Super Barrier Rectifier Technology
- Low Forward Voltage Drop
- Excellent High Temperature Stability
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **“Green” Molding Compound (No Br, Sb)**

Mechanical Data

- Case: POWERDI[®]5
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 ③
- Weight: 0.093 grams (approximate)



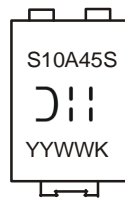
Note: Pins Left & Right must be electrically connected at the printed circuit board.

Ordering Information (Note 2)

Part Number	Case	Packaging
SBR10A45SP5-13	POWERDI [®] 5	5000/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see *EU Directive 2002/95/EC Annex Notes*
 2. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



S10A45S = Product Type Marking Code
 ⌋|| = Manufacturers' code marking
 K = Factory designator
 YYWW = Date Code Marking
 YY = Last two digits of year (ex: 08 for 2008)
 WW = Week code (01 - 53)

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	45	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_{RM}		
Average Rectified Output Current	I_O	10	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	180	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance	$R_{\theta JA}$	102	$^\circ\text{C/W}$
Thermal Resistance Junction to Ambient (Note 3)			
Thermal Resistance Junction to Ambient (Note 4)			
Operating Temperature Range	T_J	$V_R \leq 80\% V_{RRM}$	-65 to +150
		$V_R \leq 50\% V_{RRM}$	≤ 180
		DC Forward Mode	≤ 200
Storage Temperature Range	T_{STG}	-65 to +175	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	$V_{(BR)R}$	45	-	-	V	$I_R = 0.5\text{mA}$
Forward Voltage Drop	V_F	-	0.39	-	V	$I_F = 5\text{A}, T_J = 25^\circ\text{C}$
		-	0.46	0.53		$I_F = 10\text{A}, T_J = 25^\circ\text{C}$
Leakage Current (Note 5)	I_R	-	-	400	μA	$V_R = 45\text{V}, T_J = 25^\circ\text{C}$

- Notes: 3. FR-4 PCB, 2oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
4. Polyimide PCB, 2oz. Copper, minimum recommended pad layout per <http://www.diodes.com>.
5. Short duration pulse test used to minimize self-heating effect.

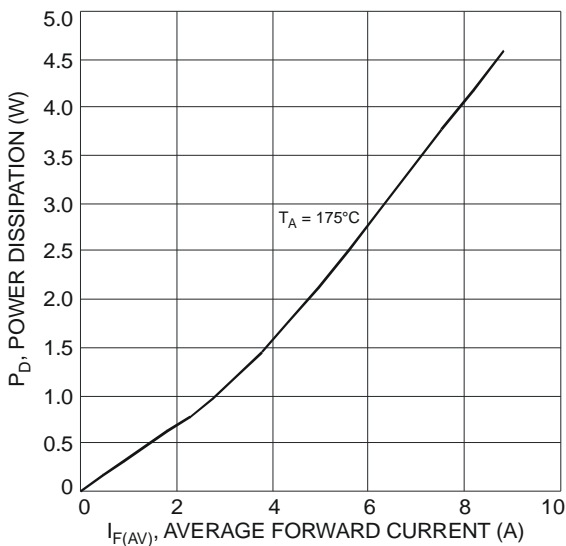


Fig. 1 Forward Power Dissipation

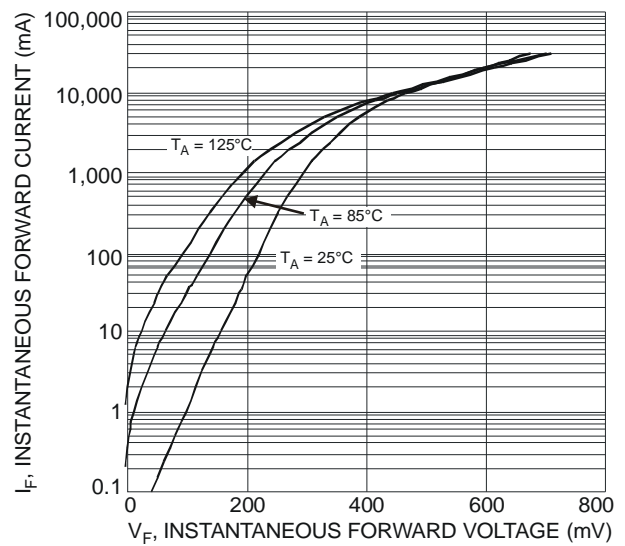


Fig. 2 Typical Forward Characteristics

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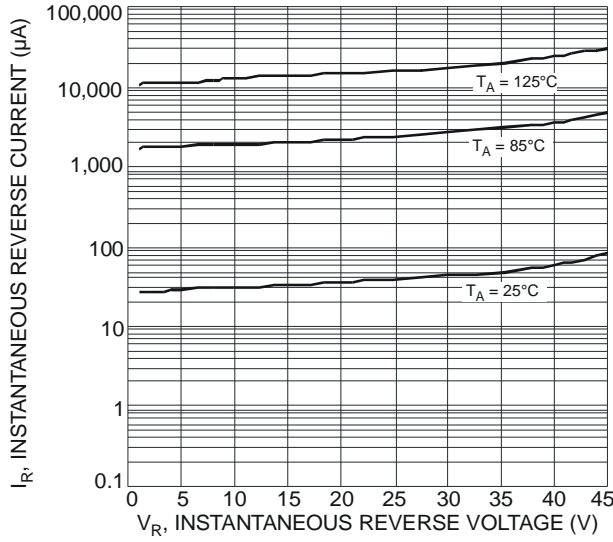


Fig. 3 Typical Reverse Characteristics

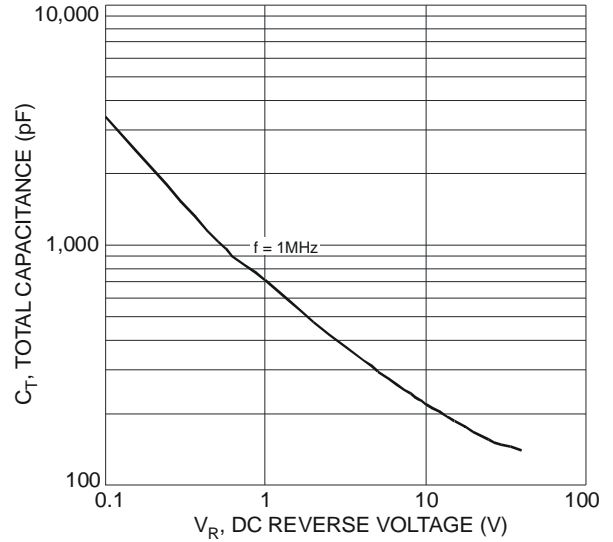


Fig. 4 Total Capacitance vs. Reverse Voltage

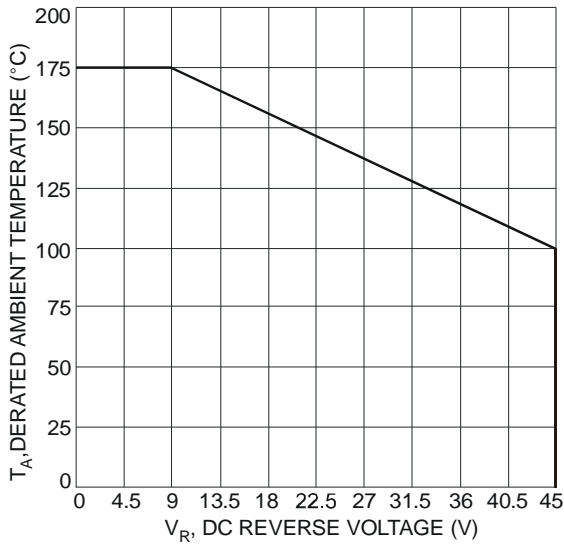


Fig. 5 Operating Temperature Derating

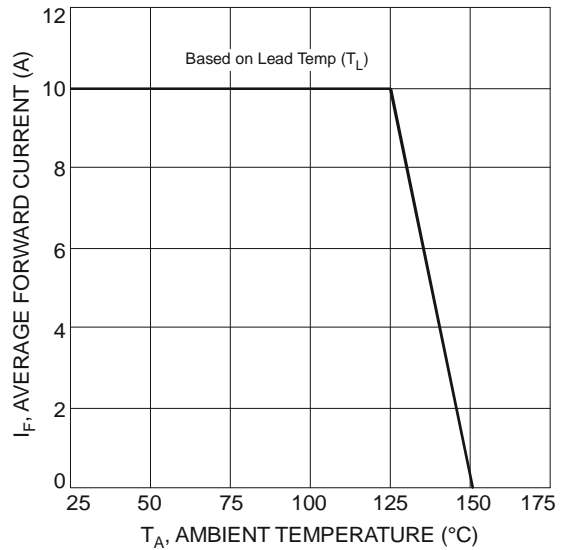
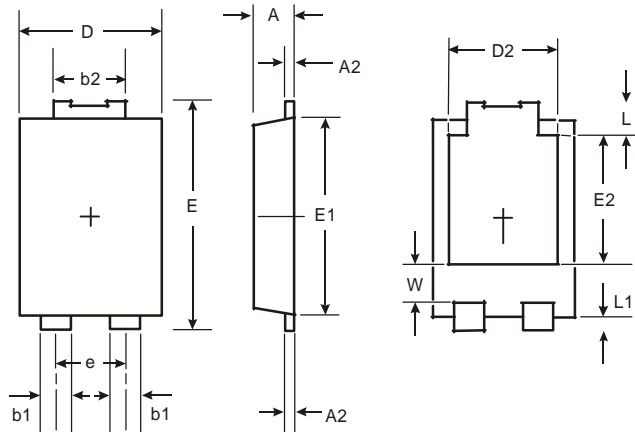


Fig. 6 Forward Current Derating Curve

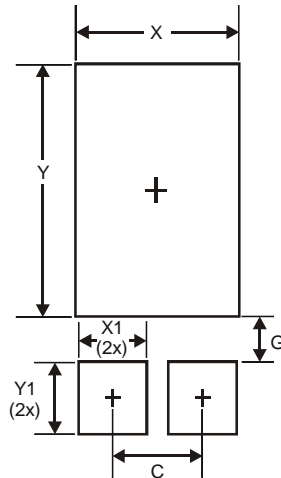
Package Outline Dimensions



POWERDI [®] 5		
Dim	Min	Max
A	1.05	1.15
A2	0.33	0.43
b1	0.80	0.99
b2	1.70	1.88
D	3.90	4.05
D2	3.054 Typ	
E	6.40	6.60
e	1.84 Typ	
E1	5.30	5.45
E2	3.549 Typ	
L	0.75	0.95
L1	0.50	0.65
W	1.10	1.41
All Dimensions in mm		

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Suggested Pad Layout



Dimensions	Value (in mm)
C	1.840
G	0.852
X	3.360
X1	1.390
Y	4.860
Y1	1.400

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